

MOSFET

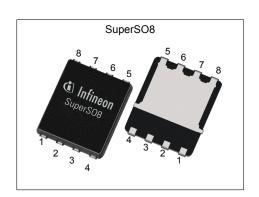
OptiMOS™ 3 Power-MOSFET, 30 V

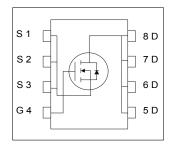
Features

- Fast switching MOSFET for SMPS
 Optimized technology for DC/DC converters
 Qualified according to JEDEC¹⁾ for target applications
 N-channel; Logic level
- Excellent gate charge x R_{DS(on)} product (FOM)
- Very low on-resistance R_{DS(on)}
- Superior thermal resistanceAvalanche rated
- Pb-free plating; RoHS compliant
- Halogen-free according to IEC61249-2-21



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Parameter	Value	Unit					
V _{DS}	30	V					
R _{DS(on),max}	3	mΩ					
I _D	122	A					











Type / Ordering Code	Package	Marking	Related Links
BSC030N03LS G	PG-TDSON-8	030N03LS	-



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1 Maximum ratings at T_A =25 °C, unless otherwise specified

Table 2 Maximum ratings

Damamatan	Connection 1	Values					
Parameter	Symbol	Min.	Тур.	Max.	Unit	Note / Test Condition	
Continuous drain current ¹⁾	I _D	- - - -	- - - -	122 77 98 62 23	A	$V_{\rm GS}$ =10 V, $T_{\rm C}$ =25 °C $V_{\rm GS}$ =10 V, $T_{\rm C}$ =100 °C $V_{\rm GS}$ =4.5 V, $T_{\rm C}$ =25 °C $V_{\rm GS}$ =4.5 V, $T_{\rm C}$ =100 °C $V_{\rm GS}$ =10 V, $T_{\rm A}$ =25 °C, $R_{\rm thJA}$ =50 K/W ²⁾	
Pulsed drain current ³⁾	I _{D,pulse}	-	-	488	Α	<i>T</i> _C =25 °C	
Avalanche current, single pulse ⁴⁾	I _{AS}	-	-	50	Α	T _C =25 °C	
Avalanche energy, single pulse	E AS	-	-	75	mJ	$I_{\rm D}$ =50 A, $R_{\rm GS}$ =25 Ω	
Reverse diode dv/dt	dv/dt	-	-	6	kV/µs	/ _D =50 A, V _{DS} =24 V, d <i>i</i> /d <i>t</i> =200 A/μs, / _{T_{j,max}=150 °C}	
Gate source voltage	V _{GS}	-20	-	20	V	-	
Power dissipation	P _{tot}	-	-	69 2.5	-	T _C =25 °C T _A =25 °C, R _{thJA} =50 K/W ²⁾	
Operating and storage temperature	T _j , T _{stg}	-55	-	150	°C	IEC climatic category; DIN IEC 68-1: 55/150/56	

2 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition	
raiailietei	Symbol	Min.	Тур.	Max.	Ullit	Note / Test Condition	
Thermal resistance, junction - case, bottom	R _{thJC}	-	-	1.8	K/W	-	
Thermal resistance, junction - case, top	R _{thJC}	-	-	18	K/W	-	
Device on PCB, 6 cm ² cooling area ²⁾	R _{thJA}	-	-	50	K/W	-	

¹⁾ Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature at 25°C. For higher case temperature please refer to Diagram 2. De-rating will be required based on the actual

environmental conditions.

2) Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm2 (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

3) See Diagram 3 for more detailed information

⁴⁾ See Diagram 13 for more detailed information



Electrical characteristics

at T_j=25 °C, unless otherwise specified

Table 4 **Static characteristics**

D	0		Values				
Parameter	Symbol	Min.	Min. Typ.		Unit	Note / Test Condition	
Drain-source breakdown voltage	V _{(BR)DSS}	30	-	-	V	V _{GS} =0 V, I _D =1 mA	
Gate threshold voltage	V _{GS(th)}	1	-	2.2	V	V _{DS} =V _{GS} , I _D =250 μA	
Zero gate voltage drain current	I _{DSS}	-	0.1 10	1 100	μA	V _{DS} =30 V, V _{GS} =0 V, T _j =25 °C V _{DS} =30 V, V _{GS} =0 V, T _j =125 °C	
Gate-source leakage current	I _{GSS}	-	10	100	nA	V _{GS} =20 V, V _{DS} =0 V	
Drain-source on-state resistance	R _{DS(on)}	-	3.8 2.5	4.7	mΩ	V _{GS} =4.5 V, I _D =30 A V _{GS} =10 V, I _D =30 A	
Gate resistance	R _G	0.7	1.5	2.6	Ω	-	
Transconductance	g fs	49	98	-	S	$ V_{DS} > 2 I_D R_{DS(on)max}, I_D = 30 A$	

Table 5 **Dynamic characteristics**

Parameter	Ol	Values			11		
Parameter	Symbol	Min.	Тур.	Max.	Unit	Note / Test Condition	
Input capacitance ¹⁾	C _{iss}	-	3200	4300	pF	V _{GS} =0 V, V _{DS} =15 V, <i>f</i> =1 MHz	
Output capacitance ¹⁾	Coss	-	1200	1600	pF	V _{GS} =0 V, V _{DS} =15 V, <i>f</i> =1 MHz	
Reverse transfer capacitance	C _{rss}	_	66	-	pF	V _{GS} =0 V, V _{DS} =15 V, f=1 MHz	
Turn-on delay time	$t_{\sf d(on)}$	-	7.3	-	ns	$V_{\rm DD}$ =15 V, $V_{\rm GS}$ =10 V, $I_{\rm D}$ =30 A, $R_{\rm G}$ =1.6 Ω	
Rise time	t _r	-	5.2	-	ns	$V_{\rm DD}$ =15 V, $V_{\rm GS}$ =10 V, $I_{\rm D}$ =30 A, $R_{\rm G}$ =1.6 Ω	
Turn-off delay time	$t_{ m d(off)}$	-	29	-	ns	$V_{\rm DD}$ =15 V, $V_{\rm GS}$ =10 V, $I_{\rm D}$ =30 A, $R_{\rm G}$ =1.6 Ω	
Fall time	t _f	-	4.8	-	ns	$V_{\rm DD}$ =15 V, $V_{\rm GS}$ =10 V, $I_{\rm D}$ =30 A, $R_{\rm G}$ =1.6 Ω	

Gate charge characteristics²⁾ Table 6

Damamatan	0		Values			N	
Parameter	Symbol	Min.	Тур.	Max.	Unit	Note / Test Condition	
Gate to source charge	Q _{gs}	-	9.5	13	nC	$V_{\rm DD}$ =15 V, $I_{\rm D}$ =30 A, $V_{\rm GS}$ =0 to 4.5 V	
Gate charge at threshold	$Q_{g(th)}$	-	5.2	6.9	nC	$V_{\rm DD}$ =15 V, $I_{\rm D}$ =30 A, $V_{\rm GS}$ =0 to 4.5 V	
Gate to drain charge	$Q_{ m gd}$	-	4.6	7.6	nC	$V_{\rm DD}$ =15 V, $I_{\rm D}$ =30 A, $V_{\rm GS}$ =0 to 4.5 V	
Switching charge	Q _{sw}	-	9.0	13	nC	$V_{\rm DD}$ =15 V, $I_{\rm D}$ =30 A, $V_{\rm GS}$ =0 to 4.5 V	
Gate charge total	Q _g	-	20	27	nC	$V_{\rm DD}$ =15 V, $I_{\rm D}$ =30 A, $V_{\rm GS}$ =0 to 4.5 V	
Gate plateau voltage	V _{plateau}	-	3.0	-	V	$V_{\rm DD}$ =15 V, $I_{\rm D}$ =30 A, $V_{\rm GS}$ =0 to 4.5 V	
Gate charge total	Qg	-	42	55	-	$V_{\rm DD}$ =15 V, $I_{\rm D}$ =30 A, $V_{\rm GS}$ =0 to 10 V	
Gate charge total, sync. FET	Q _{g(sync)}	-	17	23	nC	V _{DS} =0.1 V, V _{GS} =0 to 4.5 V	
Output charge	Qoss	-	31	41	-	V _{DD} =15 V, V _{GS} =0 V	

¹⁾ Defined by design. Not subject to production test ²⁾ See "Gate charge waveforms" for parameter definition. Defined by design, not subject to production test

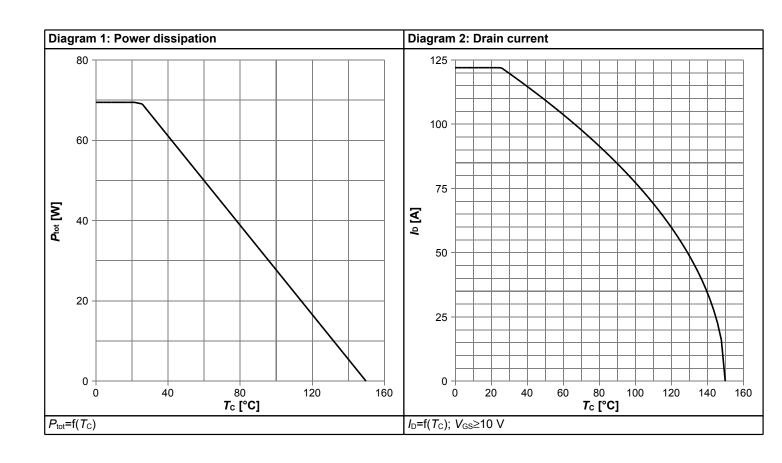


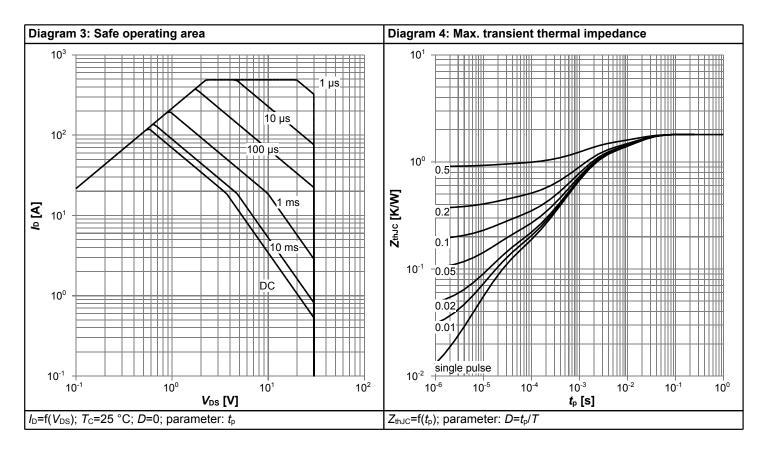
Table 7 Reverse diode

Davamatav	Cumbal	Values			11::4	Nata / Tant Can dition	
Parameter	Symbol Min. Typ		Тур.	Max.	Unit	Note / Test Condition	
Diode continuous forward current	Is	-	-	63	Α	T _C =25 °C	
Diode pulse current	I _{S,pulse}	-	-	488	Α	T _C =25 °C	
Diode forward voltage	V _{SD}	-	0.82	1.1	V	V _{GS} =0 V, I _F =30 A, T _j =25 °C	
Reverse recovery charge ¹⁾	Qrr	-	-	20	nC	V _R =15 V, I _F =I _S , di _F /dt=400 A/μs	

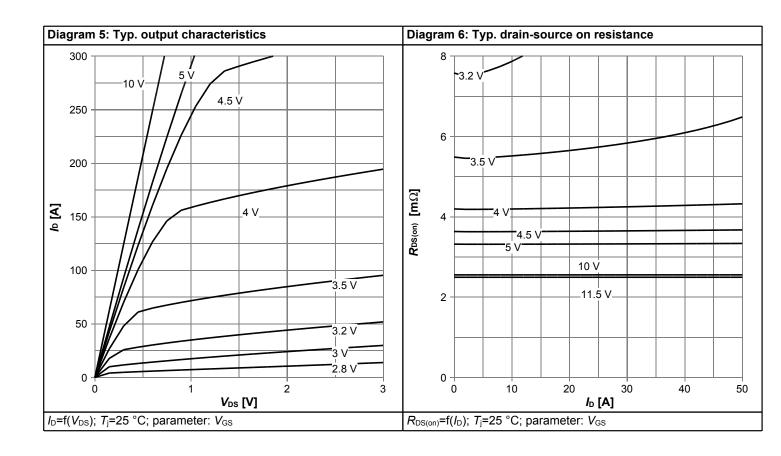


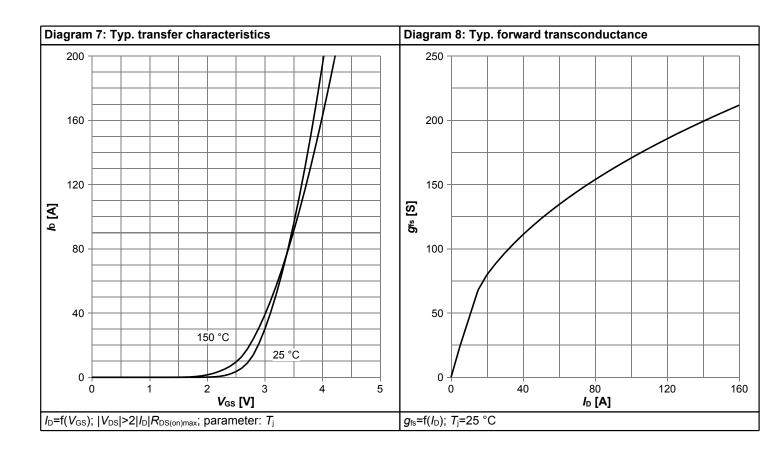
4 Electrical characteristics diagrams



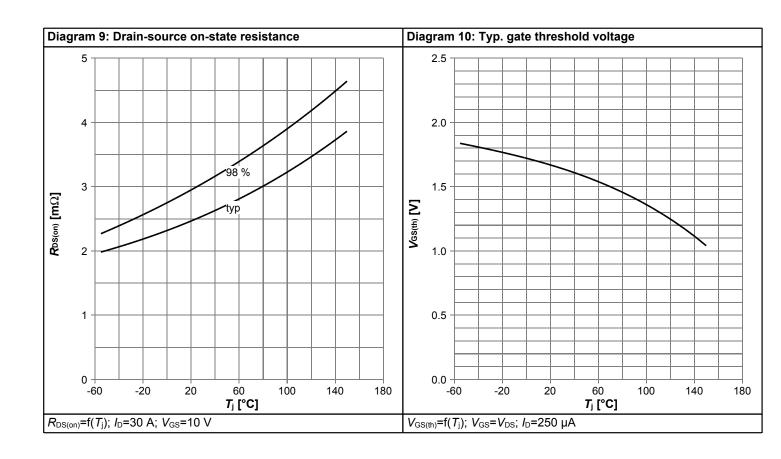


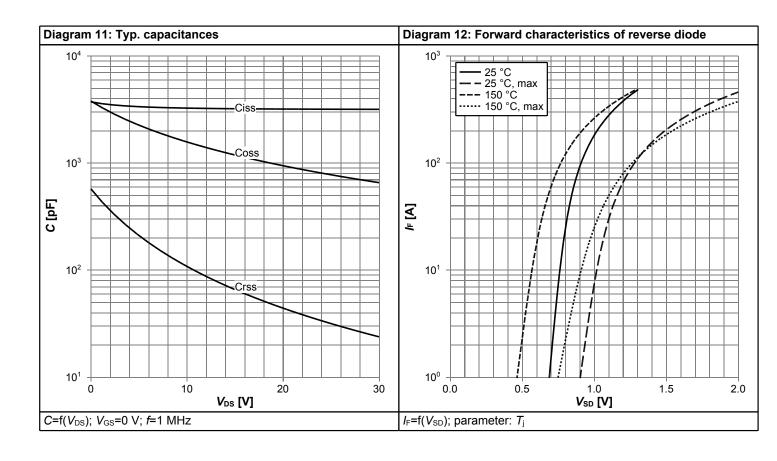




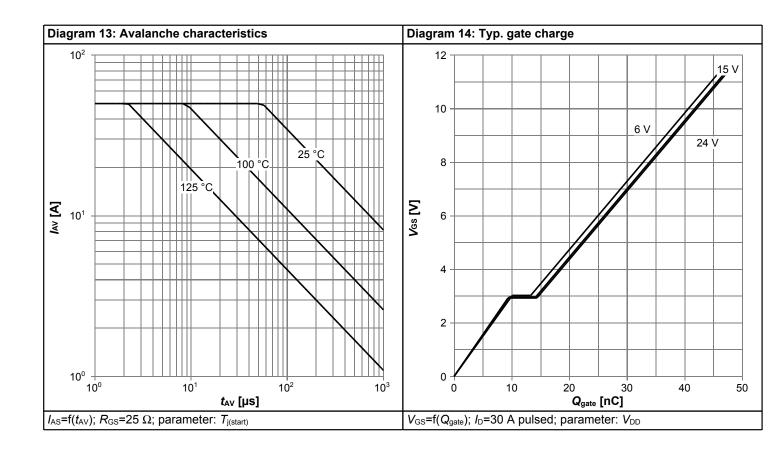


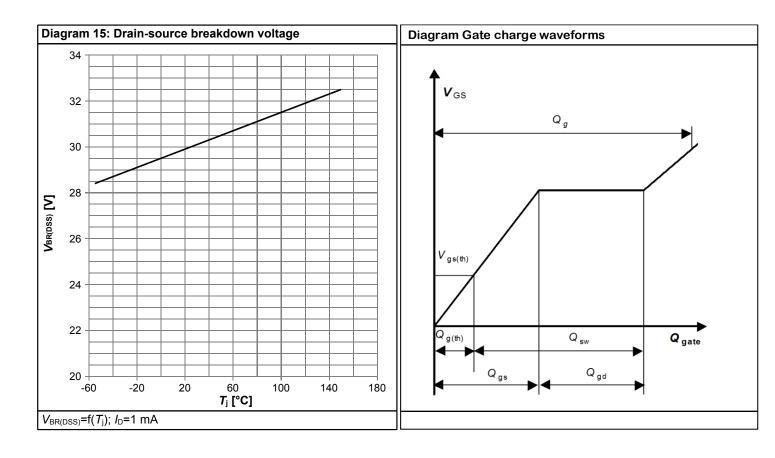






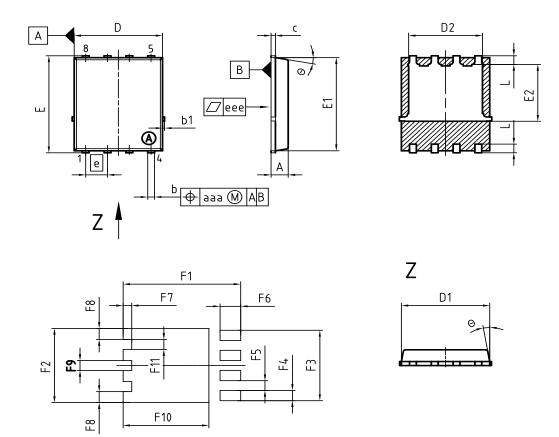








5 Package Outlines



DIM	MILLIM	ETERS	INCHES				
DIM	MIN	MAX	MIN	MAX			
Α	0.90	1.10	0.035	0.043			
b	0.34	0.54	0.013	0.021			
b1	0.02	0.22	0.001	0.008			
С	0.15	0.35	0.006	0.014			
D=D1	4.95	5.35	0.195	0.211			
D2	4.20	4.40	0.165	0.173			
ш	5.95	6.35	0.234	0.250			
E1	5.70	6.10	0.224	0.240			
E2	3.40	3.80	0.134	0.150			
е	1.2	27	0.050				
N		8	8				
L	0.45	0.65	0.018	0.026			
Θ	8.5°	11.5°	8.5°	11.5°			
aaa	0.2	25	0.010				
eee	0.0)5	0.002				
F1	6.75	6.95	0.266	0.274			
F2	4.60	4.80	0.181	0.189			
F3	4.36	4.56	0.172	0.180			
F4	0.55	0.75	0.022	0.030			
F5	0.52	0.72	0.020	0.028			
F6	1.10	1.30	0.043	0.051			
F7	0.40	0.60	0.016	0.024			
F8	0.60	0.80	0.024	0.031			
F9	0.53	0.73	0.021	0.029			
F10	4.90	5.10	0.193	0.201			
F11	0.53	0.73	0.021	0.029			

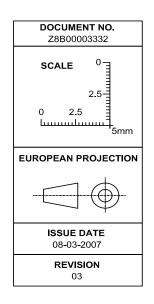


Figure 1 Outline PG-TDSON-8, dimensions in mm/inches



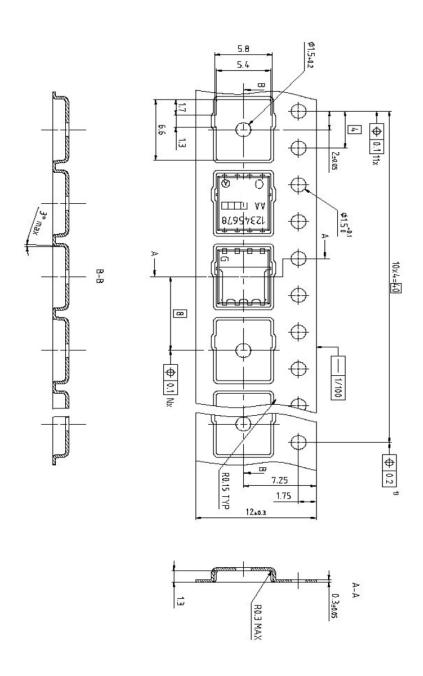


Figure 2 Outline Tape (PG-TDSON-8), dimensions in mm



Revision History

BSC030N03LS G

Revision: 2020-08-26, Rev. 2.0

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.0	2020-08-26	Update current rating and footnotes

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